



ABSTRACT

The present invention provides a die-
attaching paste superior in solder cracking resistance,
used for bonding of semiconductor chips. The present
5 invention lies in a die-attaching paste comprising as
essential components:

- (A) a hydrocarbon having a number-average
molecular weight of 500 to 5,000 and at least one
double bond in the molecule, or its derivative,
- 10 (B) a reactive diluent,
- (C) a radical polymerization catalyst, and
- (D) a filler.

